Cypress Semiconductor Corp, 198 Champion Court, San Jose, CA 95134, Tel: (408)943-2600

PRODUCT INFORMATION NOTIFICATION

PIN: PIN145273 **Date:** March 13, 2014

Subject: Improvement of Cypress Minnesota Back-End-of-Line Integration for 130nm SONOS Product Families

To: PCN ADMINISTRATOR
CYPRESS PCN ADMIN
pcn_adm@cypress.com

Change Type: Minor

Description of Change:
Cypress announces the qualification of industry standard Back-End-of-Line (BEOL) integration for robust device performance on the 130nm SONOS process technology. This change aligns our internal Cypress Minnesota process, Titanium Tungsten (TiW) based metal stack, with the industry-wide Best Known Method Titanium Nitride (TiN) based metal stack.

Product datasheets remain the same and can be downloaded from the Cypress Website (www.cypress.com).

Benefit of Change:
This change will provide continuous improvement and alignment with industry standards.

Affected Part Numbers: 1005
Affected Parts: Please see attached Affected Parts List

Customer Part Numbers Affected:
Affected Parts: N/A

Qualification Status:
As per the Cypress specified list of changes, this change has been qualified through a series of tests identified in Qualification Test Plans (QTP) report No. 123907, 132301 and 132302 The QTP report can be found in the attachment to this notification or by visiting www.cypress.com, typing the QTP number in the keyword search window.

Approximate Implementation Date:
Effective with the date of this notification, the affected part numbers in the attached file will transition to the new BEOL integration process.

Anticipated Impact:
This process change will align the 130nm SONOS BEOL process to Industry best practices. The integration process is tuned to ensure that there are no electrical changes, and therefore no impact to product characteristics. Products manufactured with the new process are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
This is an information only announcement. No response is required

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration